

## HTD2A80AS 3 Quadrants 2A TRIAC

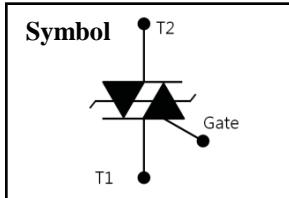
### FEATURES

- Repetitive Peak Off-State Voltage : 1000V
- R.M.S On-State Current ( $I_{T(RMS)} = 2A$ )
- Gate Trigger Current : 10mA
- $dV/dt \geq 500V/\mu s$
- High Voltage Blocking Capability

### General Description

Intended for use in AC static switching and industrial control systems, driving low power highly inductive load like solenoid, pump, fan ad micro-motor.

$V_{DRM} = 1000\text{ V}$
$I_{T(RMS)} = 2\text{ A}$
$I_{TSM} = 17\text{ A}$
$I_{GT} = 10\text{ mA}$



### Absolute Maximum Ratings ( $T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Ratings	Unit
$V_{DRM}$	Repetitive Peak Off-State Voltage	Sine wave, 50/60Hz, Gate open	1000	V
$V_{RRM}$	Repetitive Peak Reverse Voltage		1000	V
$V_{DSM}$	Non-Repetitive Surge Peak Off-State Voltage		1100	V
$V_{RSM}$	Non-Repetitive Peak Reverse Voltage		1100	V
$I_{T(RMS)}$	R.M.S. On-State Current	Full sine wave, $T_C = 95^\circ\text{C}$	2	A
$I_{TSM}$	Non-Repetitive Surge Peak On-State Current	Full sine wave, 50Hz/60Hz	16/17	A
$I^2t$	Fusing Current	$t = 10\text{ms}$	1.28	$\text{A}^2\text{s}$
$P_{GM}$	Forward Peak Gate Power Dissipation	$T_J = 80^\circ\text{C}$	1	W
$P_{G(AV)}$	Forward Average Gate Power Dissipation	$T_J = 80^\circ\text{C}$	0.2	W
$I_{GM}$	Peak Gate Current	$tp \leq 2\text{us}, T_J = 80^\circ\text{C}$	1	A
$T_J$	Operating Junction Temperature		-40~+125	$^\circ\text{C}$
$T_{STG}$	Storage Temperature		-40~+150	$^\circ\text{C}$

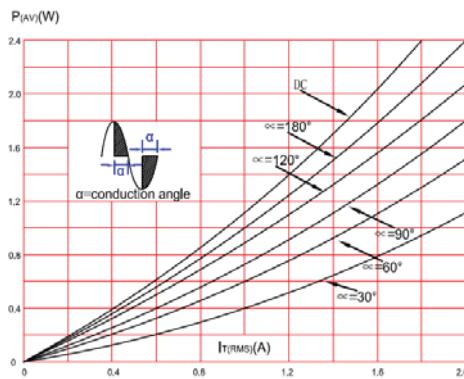
### Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I <sub>DRM</sub>	Repetitive Peak Off-State Current	V <sub>D</sub> = V <sub>DRM</sub>	T <sub>J</sub> =25°C	-	-	10 uA
			T <sub>J</sub> =125°C	-	-	500 uA
I <sub>RRM</sub>	Repetitive Peak Reverse Current	V <sub>R</sub> = V <sub>RRM</sub>	T <sub>J</sub> =25°C	-	-	10 uA
			T <sub>J</sub> =125°C	-	-	500 uA
I <sub>GT</sub>	Gate Trigger Current	V <sub>D</sub> = 12V, R <sub>L</sub> =30Ω	1+	-	-	6 mA
			1-, 3-	-	-	10 mA
V <sub>GT</sub>	Gate Trigger Voltage	V <sub>D</sub> = 12V, R <sub>L</sub> =30Ω	1+, 1-, 3-	-	-	1.5 V
V <sub>GD</sub>	Non-Trigger Gate Voltage	V <sub>D</sub> = 2/3V <sub>DRM</sub> , R <sub>L</sub> =3.3KΩ, T <sub>J</sub> =125°C		0.2	-	- V
I <sub>L</sub>	Latching Current	I <sub>G</sub> = 1.2I <sub>GT</sub>	1+, 3-	-	-	15 mA
			1-	-	-	25 mA
I <sub>H</sub>	Holding Current	I <sub>T</sub> = 100mA	-	-	10	mA
V <sub>TM</sub>	Peak On-State Voltage	I <sub>T</sub> = 2A, t <sub>p</sub> = 380uS	-	-	1.6	V
dv/dt	Critical Rate of Rise of Off-State Voltage	V <sub>D</sub> = 2/3 V <sub>DRM</sub> , Gate open, T <sub>J</sub> =125°C	500	-	-	V/us

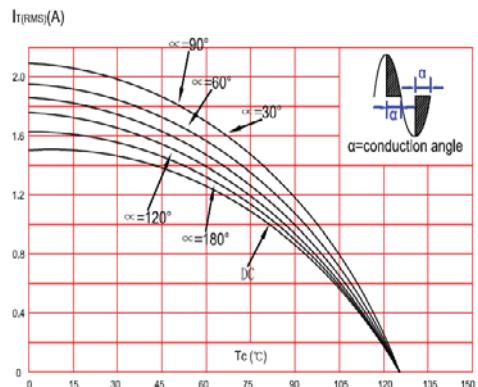
### Thermal Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
R <sub>θJC</sub>	Thermal Resistance	Junction to Case			4.5	°C/W

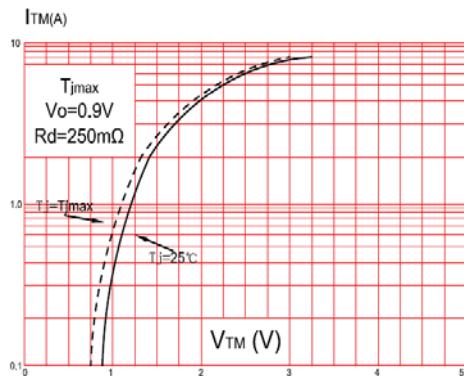
## Typical Characteristics



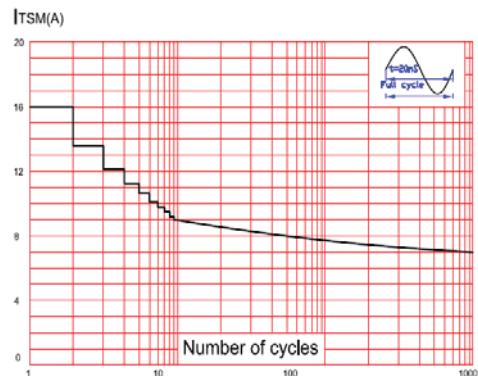
**Fig 1. R.M.S. current vs. Power dissipation**



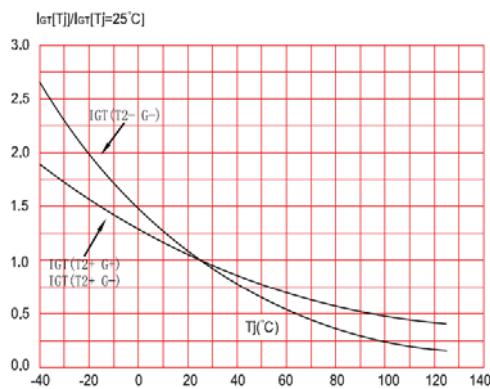
**Fig 2. R.M.S. current vs. Case temperature**



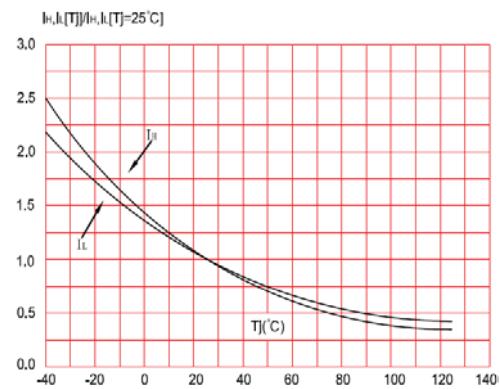
**Fig 3. Surge on state characteristics**



**Fig 4. Surge on state current rating**



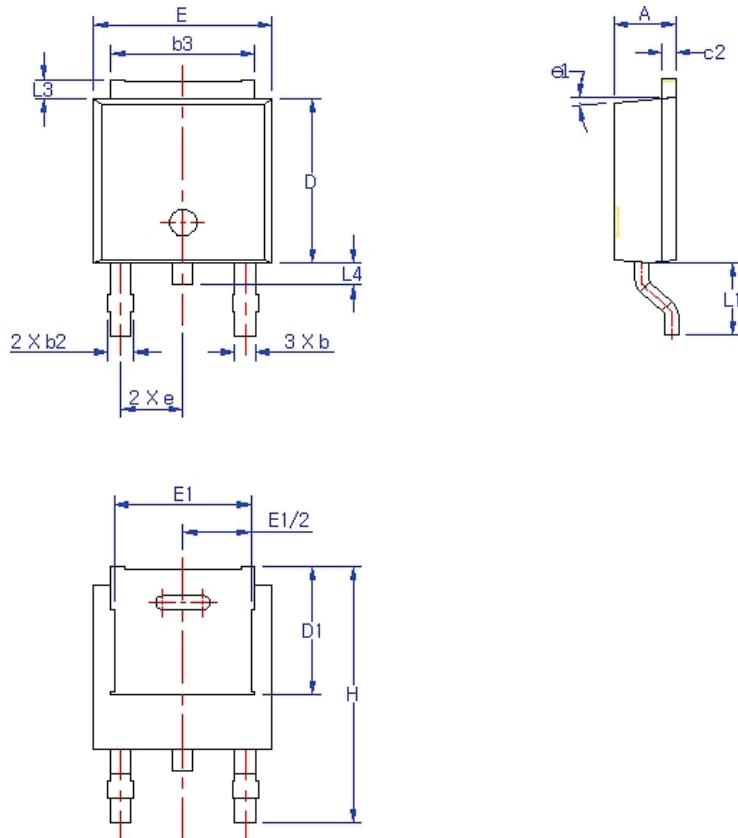
**Fig 5. Gate trigger current vs. junction temperature**



**Fig 6. Holding and latching current vs. junction temperature**

## Package Dimension

TO-252



SYMBOL	MIN	NOM	MAX
A	2.20	2.30	2.40
A1 (▼)	0.00	-	0.127
b	0.66	0.76	0.86
b2	-	-	0.96
b3	5.04	5.34	5.64
c2	0.40	0.50	0.60
D	5.90	6.10	6.30
D1	(4.75)		
E	6.40	6.60	6.80
E1	(5.04)		
e	2.30 BSC		
H	9.20	9.50	9.80
L	1.27	1.47	1.67
L1	2.50	2.70	2.90
L2	0.508 BSC		
L3	0.50	0.70	0.90
L4	0.60	0.80	1.00
θ	0°	-	10°
θ1	(5°)		